

PROCEEDINGS



# ***Three-Dimensional Image Processing, Measurement (3DIPM), and Applications 2014***

**Atila M. Baskurt**  
**Robert Sitnik**  
*Editors*

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# Contents

v *Conference Committee*

---

## **SESSION 1 3D PROCESSING, INDEXING, AND MODELING**

---

- 9013 02 **Temporal consistent depth map upscaling for 3DTV** [9013-1]  
S. Schwarz, M. Sjöström, R. Olsson, Mid Sweden Univ. (Sweden)
- 9013 03 **Feature enhancing aerial lidar point cloud refinement** [9013-2]  
Z. Gao, U. Neumann, The Univ. of Southern California (United States)
- 9013 04 **VOLUMNECT: measuring volumes with Kinect** [9013-3]  
B. Quintino Ferreira, M. Griné, D. Gameiro, J. P. Costeira, Univ. Técnica de Lisboa (Portugal);  
B. Sousa Santos, Univ. de Aveiro (Portugal) and Instituto de Engenharia Electrónica e  
Telemática de Aveiro (Portugal)
- 9013 05 **3D mesh indexing based on structural analysis** [9013-4]  
M. Hachani, National Engineering School of Tunis (Tunisia) and Lab. d'Informatique de  
Robotique et de Microelectronique de Montpellier, CNRS, Univ. Montpellier 2 (France);  
A. Ouled Zaid, National Engineering School of Tunis (Tunisia); W. Puech, Lab. d'Informatique  
de Robotique et de Microelectronique de Montpellier, CNRS, Univ. Montpellier 2 (France)

---

## **SESSION 2 3D PATTERN RECOGNITION AND REAL TIME PROCESSING**

---

- 9013 06 **Real-time 3D human pose recognition from reconstructed volume via voxel classifiers**  
[9013-5]  
B. Yoo, Samsung Advanced Institute of Technology (Korea, Republic of) and Korea  
Advanced Institute of Science and Technology (Korea, Republic of); C. Choi, J.-J. Han,  
C. Lee, W. Kim, S. Suh, D. Park, Samsung Advanced Institute of Technology (Korea,  
Republic of); J. Kim, Korea Advanced Institute of Science and Technology (Korea,  
Republic of)
- 9013 07 **Model-based 3D human shape estimation from silhouettes for virtual fitting** [9013-6]  
S. Saito, Keio Univ. (Japan); M. Kouchi, M. Mochimaru, National Institute of Advanced  
Industrial Science and Technology (Japan); Y. Aoki, Keio Univ. (Japan)
- 9013 08 **3D face recognition via conformal representation** [9013-7]  
J. Han, C. Fang, X. Ding, J. Sun, Tsinghua Univ. (China); X. D. Gu, Stony Brook Univ. (United  
States)

---

**SESSION 3 3D IMAGING SYSTEMS**

---

- 9013 09 **Real-time 3D shape measurement system with full temporal resolution and spatial resolution** [9013-9]  
K. Zhong, Z. Li, Huazhong Univ. of Science and Technology (China); X. Zhou, Wuhan Univ. (China); G. Zhan, X. Liu, Y. Shi, C. Wang, Huazhong Univ. of Science and Technology (China)
- 9013 0A **New concept of technology chain for 3D/4D content generation and display** [9013-10]  
M. Kujawińska, R. Sitnik, T. Kozacki, Warsaw Univ. of Technology (Poland)
- 9013 0B **Low-cost structured-light 3D capture system design** [9013-11]  
J. Dong, Purdue Univ. (United States); K. R. Bengtson, Hewlett-Packard Co. (United States); B. F. Robinson, J. P. Allebach, Purdue Univ. (United States)

---

**INTERACTIVE PAPER SESSION**

---

- 9013 0C **Human machine interface by using stereo-based depth extraction** [9013-12]  
C.-K. Liao, C.-H. Wu, H.-Y. Lin, T.-T. Chang, T.-Y. Lin, P.-K. Huang, IMEC (Taiwan)
- 9013 0D **Tabu search for human pose recognition** [9013-14]  
W. Dyce, Univ. Montpellier 2 (France); N. Rodriguez, Lab. d'Informatique de Robotique et de Microelectronique de Montpellier (France); B. Lange, Univ. Pierre et Marie Curie (France); S. Andary, A. Seilles, NaturalPad (France)
- 9013 0E **A multiple wavelength unwrapping algorithm for digital fringe profilometry based on spatial shift estimation** [9013-16]  
P. Cao, J. Xi, Y. Yu, Q. Guo, Univ. of Wollongong (Australia)
- 9013 0F **Experimental demonstration of parallel phase-shifting digital holography under weak light condition** [9013-17]  
L. Miao, Kobe Univ. (Japan); T. Tahara, P. Xia, Y. Ito, Kyoto Institute of Technology (Japan); K. Nitta, Kobe Univ. (Japan); Y. Awatsuji, Kyoto Institute of Technology (Japan); O. Matoba, Kobe Univ. (Japan)
- 9013 0G **A novel global color correction method for 3D content** [9013-18]  
P. Yver, S. Kramm, A. Bensrhair, Institut National des Sciences Appliquées de Rouen (France); E. Azzam, StereoLabs (France)

*Author Index*

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**Robert Sitnik**, Warsaw University of Technology (Poland)

- 2 3D Pattern Recognition and Real Time Processing  
**William Puech**, Laboratoire d'Informatique de Robotique et de  
Microelectronique de Montpellier (France)
- 3 3D Imaging Systems  
**William Puech**, Laboratoire d'Informatique de Robotique et de  
Microelectronique de Montpellier (France)